# DATA SHEET



# **BIPOLAR ANALOG INTEGRATED CIRCUIT**

# $\mu$ PC844GR-9LG, $\mu$ PC4744GR-9LG

# SINGLE POWER SUPPLY, HIGH SPEED, WIDE BAND, QUAD OPERATIONAL AMPLIFIERS

#### <R> DESCRIPTION

The  $\mu$ PC844GR-9LG,  $\mu$ PC4744GR-9LG are a high speed version of the operational amplifier  $\mu$ PC451GR-9LG,  $\mu$ PC324GR-9LG for general single power supply use with high speed pulse response and high stabilization. A high speed PNP transistor is used in the circuit which improves the characteristics such as a slew rate, gain-bandwidth product, stabilization of the withstand load capacitance, with no crossover distortion compared to  $\mu$ PC451GR-9LG,  $\mu$ PC324GR-9LG.

Therefore,  $\mu$ PC844GR-9LG,  $\mu$ PC4744GR-9LG can be used in a wide range of application circuits for single power supply AC amplifier, active filters, line driver and an amplifier for light receiving element etc.

The  $\mu$  PC844GR-9LG which expands temperature type is suited for wide operating ambient temperature use, and  $\mu$ PC4744GR-9LG is used for general purposes.

 $\mu$  PC842GR-9LG,  $\mu$  PC4742GR-9LG which are dual types with the same circuit configuration are also available as series of operational amplifiers.

#### <R> FEATURES

• Slew Rate (Av = +1) 7 V/ $\mu$ s (TYP.) (V<sup>+</sup> = +5 V, V<sup>-</sup> = GND) • Stability to capacitive loads (load capacity, 1000 pF)

• Gain Band Width Product 3.5 MHz (TYP.)

Internal frequency compensation

Input Offset Voltage 12 mV (TVD)

Output short-circuit protection

• Input Offset Voltage ±2 mV (TYP.)

 A pin connection (pin compatible) of a standard quad operational amplifier.

Input Offset Current ±6 nA (TYP.)
 Wide operating ambient temperature range

 $\mu$  PC844GR-9LG: T<sub>A</sub> = -40 to +125°C,  $\mu$  PC4744GR-9LG: T<sub>A</sub> = -40 to +85°C

• Small Package (The mounting area is reduced to half compared to the conventional 14-pin plastic SOP (1.27 mm pitch))

# <R> ORDERING INFORMATION

Part Number	Selected Grade	Package	Package Type
μPC844GR-9LG-E1-A Note	Standard	14-pin plastic TSSOP (5.72 mm(225))	• 16 mm wide embossed taping
			<ul> <li>Pin 1 on draw-out side</li> </ul>
$\mu$ PC844GR-9LG-E2-A $^{ m Note}$	Standard	14-pin plastic TSSOP (5.72 mm(225))	• 16 mm wide embossed taping
			<ul> <li>Pin 1 at take-up side</li> </ul>
$\mu$ PC4744GR-9LG-E1-A $^{ m Note}$	Standard	14-pin plastic TSSOP(5.72 mm(225))	• 16 mm wide embossed taping
			<ul> <li>Pin 1 on draw-out side</li> </ul>
$\mu$ PC4744GR-9LG-E2-A $^{ m Note}$	Standard	14-pin plastic TSSOP(5.72 mm(225))	• 16 mm wide embossed taping
			<ul> <li>Pin 1 at take-up side</li> </ul>

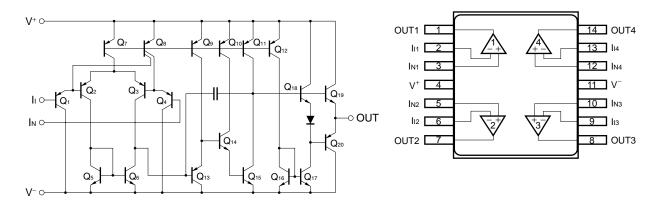
Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

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# **EQUIVALENT CIRCUIT (1/4 Circuit)**

# <R> PIN CONFIGURATION (Marking side)



# <R> ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Parameter	Symbol	μPC844GR-9LG	μ PC4744GR-9LG	Unit
Voltage between V <sup>+</sup> and V <sup>- Note1</sup>	V <sup>+</sup> - V <sup>-</sup>	-0.3	V	
Differential Input Voltage	VID	±	V	
Input Voltage Note2	Vı	V - 0.3 t	V	
Output applied Voltage Note3	Vo	$V^{-} - 0.3 \text{ to } V^{+} + 0.3$		V
Total Power Dissipation Note4	Рт	5	mW	
Output Short Circuit Duration Note5	<b>t</b> s	Indefinite		s
Operating Ambient Temperature	TA	-40 to +125	-40 to +85	°C
Storage Temperature	Tstg	−55 to +150	-55 to +125	°C

**Note1.** Note that reverse connections of the power supply may damage ICs.

- 2. The input voltage is allowed to input without damage or destruction independent of the magnitude of V<sup>+</sup>. Either input signal is not allowed to go negative by more than 0.3 V. In addition, the input voltage that operates normally as an operational amplifier is within the Common Mode Input Voltage range of an electrical characteristic.
- **3.** A range where input voltage can be applied to an output pin externally with no deterioration or damage to the feature (characteristic). The input voltage can be applied regardless of the electric supply voltage. This specification which includes the transition state such as electric power ON/OFF must be kept.
- **4.** This is the value of when the glass epoxy substrate (size: 100 mm x 100 mm, thickness: 1 mm, 15% of the substrate area where only one side is copper foiled is filling wired) is mounted.

Note that restrictions will be made to the following conditions for each product, and the derating ratio depending on the operating ambient temperature.

 $\mu$  PC844GR-9LG: Derate at –7.0 mW/°C when T<sub>A</sub> > 71°C.

(Junction – ambient thermal resistance  $R_{th(J-A)} = 144$ °C/W)

 $\mu$ PC4744GR-9LG: Derate at –7.0 mW/°C when T<sub>A</sub> > 46°C.

(Junction – ambient thermal resistance  $R_{th(J-A)} = 144^{\circ}C/W$ )

5. Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4.



# RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Power Supply Voltage (Split)	V <sup>±</sup>	±1.5		±16	V
Power Supply Voltage (V = GND)	V <sup>+</sup>	+3	+5 to +30	+32	V
Output Current	lo			±10	mA
Capacitive Load (A <sub>V</sub> = +1)	CL			1000 Note	pF

**Note** This is the value during a feedback resistance ( $R_f$ ) = 0  $\Omega$ .

# <R> ELECTRICAL CHARACTERISTICS

 $T_A = 25^{\circ}C, V^{\pm} = \pm 15 V$ 

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Offset Voltage	Vio			±2	±6	mV
Input Offset Current	lio			±6	±75	nA
Input Bias Current Note1	lв			130	500	nA
Large Signal Voltage Gain	Av	$R_L \ge 2 \text{ k}\Omega$ , $V_0 = \pm 10 \text{ V}$	25000	300000		
Circuit Current Note2	Icc	Io = 0 A		7.5	11	mA
Common Mode Rejection Ratio	CMR		70	86		dB
Supply Voltage Rejection Ratio	SVR		70	93		dB
Output Voltage Swing	V <sub>Om1</sub>	R <sub>L</sub> = 10 kΩ	<b>⊥12</b> 7	+14		V
			±13.7	-14.3		V
	V <sub>Om2</sub>	$R_L \ge 2 \ k\Omega$	±13.5			٧
Common Mode Input Voltage Range	Vісм		V <sup>-</sup>		V <sup>+</sup> – 1.8	٧
Slew Late	SR	A <sub>V</sub> = +1 (rise)		8.5		V/μs
Gain Band Width Product	GBW	f = 100 kHz		3.5		MHz
Channel Separation		f = 20 Hz to 20 kHz		120		dB

 $T_A = 25^{\circ}C, V^+ = +5 V, V^- = GND$ 

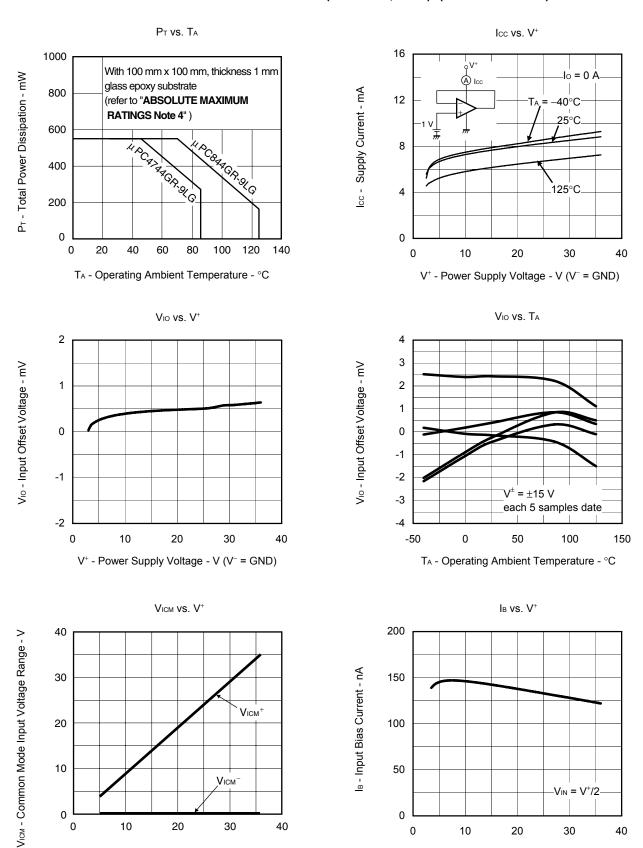
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Offset Voltage	Vio			±2	±5	mV
Input Offset Current	lio			±6	±75	nA
Input Bias Current Note1	Ів			150	500	nA
Large Signal Voltage Gain	Av	$R_L \ge 2 \ k\Omega$	25000	300000		
Circuit Current Note2	Icc	Io = 0 A		6	9	mA
Common Mode Rejection Ratio	CMR		70	80		dB
Supply Voltage Rejection Ratio	SVR		70	95		dB
Output Voltage Swing	Vom	$R_L \ge 2 \text{ k}\Omega$ (Connect to GND)	3.7	4		.,
			0	0		V
Common Mode Input Voltage Range	VICM		0		V <sup>+</sup> – 1.8	V
Output Source Current	lo source	V <sub>IN (+)</sub> = +1 V, V <sub>IN (-)</sub> = 0 V	10	30		mA
Output Sink Current	lo sink	V <sub>IN (+)</sub> = 0 V, V <sub>IN (-)</sub> = +1 V	10	30		mA
Slew Late	SR	$A_V = +1$ (rise)		7		V/μs

**Notes1.** The input bias current flows in the direction where the IC flows out because the first stage is configured with a PNP transistor.

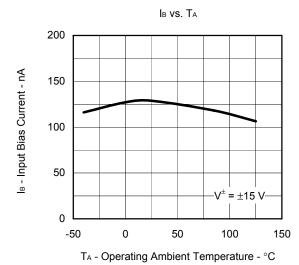
2. This is a current that flows in the internal circuit. This current will flow irrespective of the channel used.

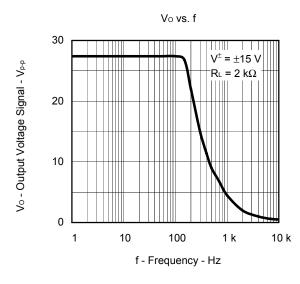
V<sup>+</sup> - Power Supply Voltage - V (V<sup>-</sup> = GND)

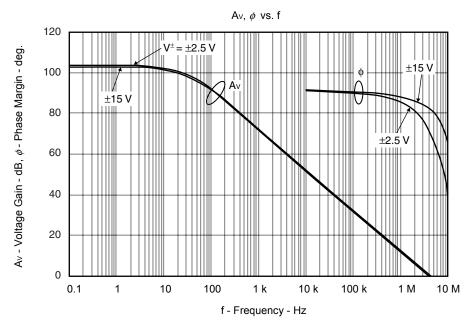
# <R> TYPICAL PERFORMANCE CHARACTERISTICS (Ta = 25°C, TYP.) (Reference value)

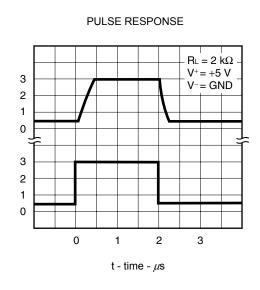


V<sup>+</sup> - Power Supply Voltage - V (V<sup>-</sup> = GND)

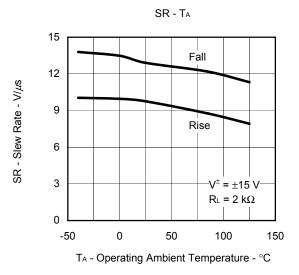


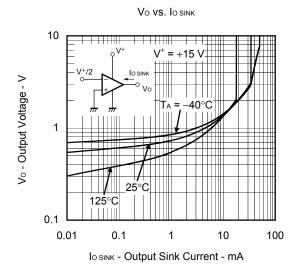


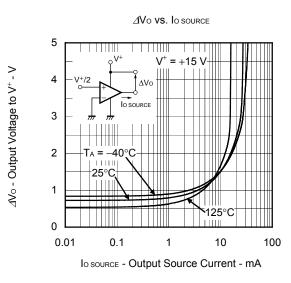




V<sub>IN</sub> - Input Voltage - V Vo - Output Voltage - V







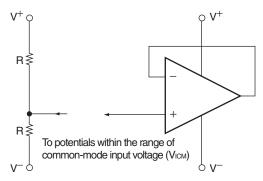


#### <R> PRECAUTIONS FOR USE

#### O The process of unused circuits

If there is an unused circuit, the following connection is recommended.

#### Process example of unused circuits



**Remark** A midpoint potential of V<sup>+</sup> and V<sup>-</sup> is applied to this example.

#### O Ratings of input/output pin voltage

When the voltage of input/output pin exceeds the absolute maximum rating, it may cause degradation of characteristics or damages, by a conduction of a parasitic diode within an IC. In addition, when the input pin may be lower than  $V^-$ , or the output pin may exceed the power supply voltage, it is recommended to make a clump circuit by a diode whose forward voltage is low (e.g.: Schottky diode) for protection.

#### O Range of common-mode input voltage

When the supply voltage does not meet the condition of electrical characteristics, the range of common-mode input voltage is as follows.

VICM (TYP.): 
$$V^-$$
 to  $V^+ - 1.8$  (V) (TA = 25°C)

During designing, temperature characteristics for use with allowance.

# O The maximum output voltage

The range of the TYP. value of the maximum output voltage when the supply voltage does not meet the condition of electrical characteristics is as follows:

$$Vom^+$$
 (TYP.):  $V^+ - 1$  (V) (TA = 25°C),  $Vom^-$  (TYP.):  $V^- + 0.7$  (V) (TA = 25°C)

During designing, consider variations in characteristics and temperature characteristics for use with allowance.

In addition, also note that the output voltage range  $(Vom^+ - Vom^-)$  becomes narrow when an output current increases.

# O Operation of output

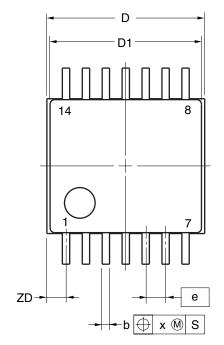
This IC will not operate an output current sinking when the output voltage is  $V^- + 0.7$  V and below. In this situation, an output voltage and its level approach to the  $V^-$  side can be improved by connecting the load resistance to an output pin /  $V^-$  intermediate by sinking current at the load resistance side. (The effect will differ depending on the flow of current in the load resistance.)

#### O Handling of ICs

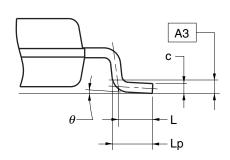
When stress is added to ICs due to warpage or bending of a board, the characteristic fluctuates due to piezoelectric effect. Therefore, pay attention to warpage or bending of a board.

# **PACKAGE DRAWINGS (Unit: mm)**

# 14-PIN PLASTIC TSSOP (5.72mm (225))



detail of lead end



# (UNIT:mm)

	(
ITEM	DIMENSIONS
D	5.15±0.15
D1	5.00±0.10
Е	4.40±0.10
HE	6.40±0.20
Α	1.20 MAX.
A1	0.10±0.05
A2	1.00±0.05
A3	0.25
b	$0.24^{+0.06}_{-0.05}$
С	0.145±0.055
L	0.50
Lp	0.60±0.15
L1	1.00±0.20
$\theta$	3°+5°
е	0.65
Х	0.10
у	0.10
ZD	0.625
	P14GR-65-9LG

# NOTE

Each lead centerline is located within 0.10mm of its true position at maximum material condition.

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# <R> RECOMMENDED SOLDERING CONDITIONS

The  $\mu$  PC844GR-9LG,  $\mu$  PC4744GR-9LG should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

# **Type of Surface Mount Device**

 $\mu$ PC844GR-9LG-A <sup>Note</sup>,  $\mu$ PC4744GR-9LG-A <sup>Note</sup>: 14-pin plastic TSSOP (5.72 mm (225))

Process	Conditions	Symbol
Infrared ray reflow	Peak temperature: 260°C, Reflow time: 60 seconds or less (at 220°C or higher),	IR60-00-3
	Maximum number of reflow processes: 3 times.	
Wave soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum	WS60-00-1
	number of flow processes: 1 time,	
	Pre-heating temperature: 120°C or below (Package surface temperature).	
Partial heating method	Pin temperature: 350°C or below,	P350
	Heat time: 3 seconds or less (Per each side of the device).	

Note Pb-free (This product does not contain Pb in external electrode and other parts.)

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

Remark Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.

# <R> REFERENCE DOCUMENTS

Document Name	Document No.	
QUALITY GRADES ON NEC SEMICONDUCTOR DEVICES	C11531E	
SEMICONDUCTOR DEVICE MOUNT MANUAL	http://www.necel.com/pkg/en/mount/index.html	
NEC SEMICONDUCTOR DEVICE RELIABILITY/QUALITY CONTROL	IEI-1212	
SYSTEM-STANDARD LINEAR IC		
REVIEW OF QUALITY AND RELIABILITY HANDBOOK	C12769E	
NEC SEMICONDUCTOR DEVICE RELIBIALITY/QUALITY CONTROL	C10983E	
SYSTEM		

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